

AMENDMENTS TO THE CLAIMS

The listing of claims below replaces all prior versions of claims in the application.

1. (Currently Amended): An optical fiber wiring method comprising the steps of:
feeding an optical fiber to pass through an adhesive ejecting nozzle having an inner diameter larger than an outer diameter of the optical fiber, to thereby obtain the optical fiber coated with the adhesive on a fiber surface, wherein an amount of the adhesive is held constant by controlling an air pressure ~~higher than an atmospheric pressure~~ for pushing out the adhesive;
and

forming optical wiring on a surface of a substrate by simultaneously ejecting the optical fiber and the adhesive.

2. (Previously Presented): The optical fiber wiring method according to Claim 1, wherein the amount of the adhesive is held constant by further controlling a speed at which the optical fiber is introduced.

3. (Previously Presented): The optical fiber wiring method according to Claim 1 or 2, wherein the optical wiring is formed on the surface of the substrate by relative movement of the substrate and the nozzle where the substrate is held fixed and the nozzle is moved horizontally.

4. (Previously Presented): The optical fiber wiring method according to Claim 1 or 2, wherein the optical wiring is formed on the surface of the substrate by relative movement of the substrate and the nozzle where the nozzle is held fixed and the substrate is moved horizontally.

5. (Previously Presented): The optical fiber wiring method according to Claim 1 or 2, wherein the optical fiber is a polymer optical fiber.

6. (Previously Presented): The optical fiber wiring method according to Claim 1 or 2, wherein the adhesive is of the type being hardened with irradiation of an ultraviolet ray, and the optical wiring is formed on the substrate by irradiating an ultraviolet ray after the optical fiber coated with the adhesive on the fiber surface has been wired on the substrate.

7. (Currently Amended): An optical fiber wiring apparatus comprising:
a liquid material ejecting unit provided with a liquid material ejecting nozzle having an inner diameter larger than an outer diameter of an optical fiber and allowing the optical fiber and the adhesive to be simultaneously fed through the nozzle;
a controller to control an air pressure ~~higher than an atmospheric pressure~~ for pushing out the adhesive; and
a stage for supporting a substrate on which the optical fiber is to be wired, wherein the liquid material ejecting unit and the stage are movable relative to each other.

8. (Previously Presented): The optical fiber wiring apparatus according to Claim 7, wherein the stage for supporting the substrate is fixed, and the nozzle is movable to form optical wiring on the substrate with the relative movement.

9. (Previously Presented): The optical fiber wiring apparatus according to Claim 7, wherein the nozzle is fixed, and the stage for supporting the substrate is movable to form optical wiring on the substrate with the relative movement.

10. (Previously Presented): The optical fiber wiring apparatus according to any one of Claims 7 to 9, wherein the adhesive is of the type being hardened with irradiation of an ultraviolet ray, and the apparatus further comprises an ultraviolet ray irradiation unit for irradiating an ultraviolet ray to harden the adhesive after the optical fiber coated with the adhesive on the fiber surface has been wired on the substrate.

11. (Previously Presented): The optical fiber wiring apparatus according to any one of Claims 7 to 9, wherein the controller controls a speed at which the optical fiber is introduced such that an amount of the adhesive is held constant.